

Chap 3 Logic Gates

- The Inverter NOT
- Logic Expression for an Inverter
- The AND Gate
- The OR Gate
- The NAND Gate NOT AND
- The NOR Gate NOT OR
- The Exclusive-OR and Exclusive-NOR Gates
- Programmable Logic OR Array
- The AND Array
- Programmable Link Process Technologies

- Fuse Technology
- Antifuse Technology
- EPROM Technology
- Flash Technology
- SRAM Technology

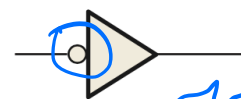
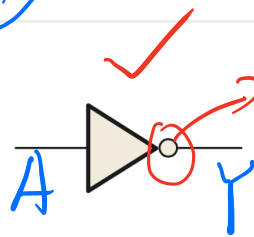
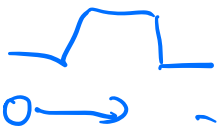
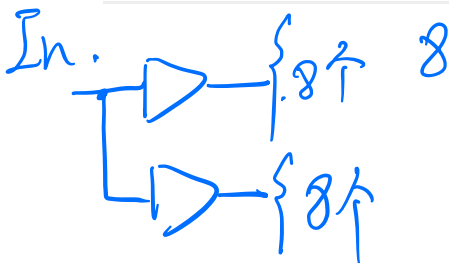
- Propagation Delay Time
- datasheets
- DC Supply Voltage
- Power Dissipation
- Input and Output Logic Levels
- Speed-Power Product (SPP)
- Fan-Out and Loading
- Unused inputs
- Troubleshooting

App

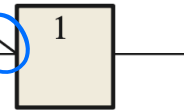
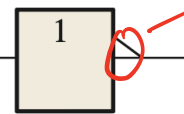
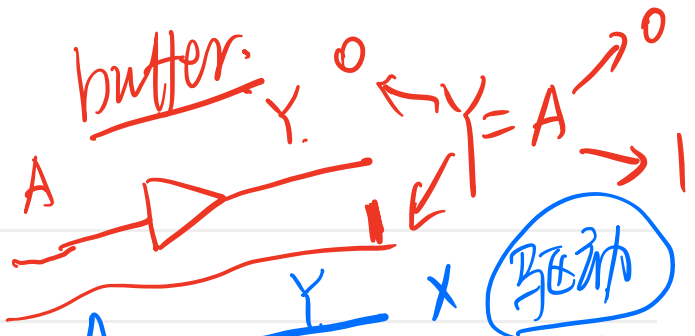
Chap 3 Logic Gates

The Inverter

16个

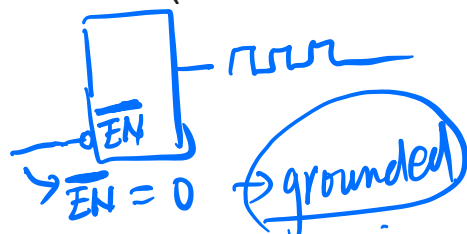
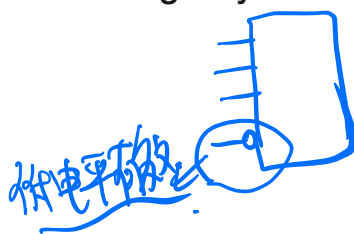


(a) Distinctive shape symbols with negation indicators



(b) Rectangular outline symbols with polarity indicators

FIGURE 3-1 Standard logic symbols for the inverter (ANSI/IEEE Std. 91-1984/Std. 91a-1991).



The polarity or level indicator is a "triangle" (\triangle) that indicates inversion when it appears on the input or output of a logic element, as shown in Figure 3-1(b). When appearing on the input, it means that a LOW level is the active or asserted input state. When appearing on the output, it means that a LOW level is the active or asserted output state.

EXAMPLE 3-1

A waveform is applied to an inverter in Figure 3-4. Determine the output waveform corresponding to the input and show the timing diagram. According to the placement of the bubble, what is the active output state?

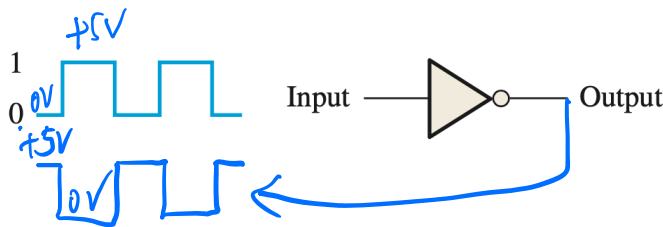


FIGURE 3-4

truth table.

Logic Expression for an Inverter

0, 1

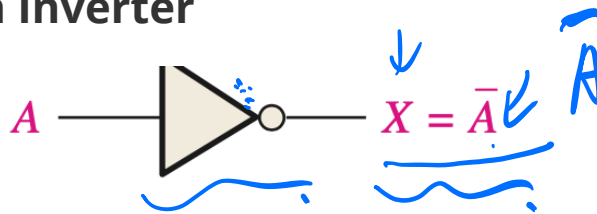


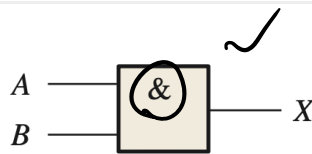
FIGURE 3-6 The inverter complements an input variable.

| A | X |
|---|---|
| 0 | 1 |
| 1 | 0 |

The AND Gate



(a) Distinctive shape



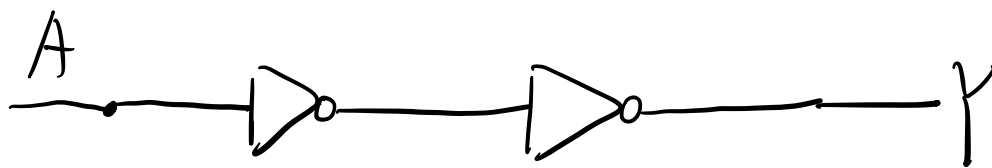
(b) Rectangular outline with the AND (&) qualifying symbol

& &

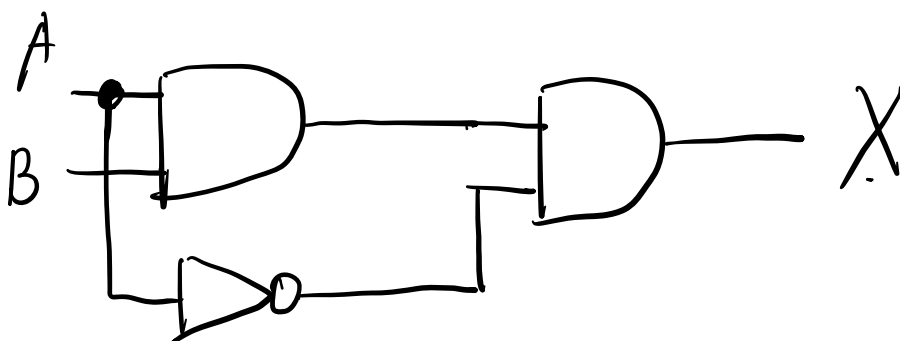
FIGURE 3-8 Standard logic symbols for the AND gate showing two inputs (ANSI/IEEE Std. 91-1984/Std. 91a-1991).

$X = AB$

| A $\rightarrow 0,1$ | B $\rightarrow 0,1$ | X |
|---------------------|---------------------|---|
| 0 | 0 | 0 |
| 0 | 1 | 0 |
| 1 | 0 | 0 |
| 1 | 1 | 1 |



$$Y = \overline{\overline{A}} = A$$



$$X = (A \cdot B) \cdot \overline{A} \rightarrow 0$$

| A | B | X | X |
|-----|-----|-----|-----|
| 0 | 0 | 0 | 0 |
| 0 | 1 | 1 | 0 |
| 1 | 0 | 1 | 0 |
| 1 | 1 | 1 | 0 |

The output X is consistently 0 for all input combinations, as indicated by the checkmark.

For an AND gate, all HIGH inputs produce a HIGH output.

TABLE 3-2

Truth table for a 2-input AND gate.

| Inputs | | Output |
|----------|----------|----------|
| <i>A</i> | <i>B</i> | <i>X</i> |
| 0 | 0 | 0 |
| 0 | 1 | 0 |
| 1 | 0 | 0 |
| 1 | 1 | 1 |

1 = HIGH, 0 = LOW

EXAMPLE 3-2

TABLE 3-3

| Inputs | | | Output |
|----------|----------|----------|----------|
| <i>A</i> | <i>B</i> | <i>C</i> | <i>X</i> |
| 0 | 0 | 0 | 0 |
| 0 | 0 | 1 | 0 |
| 0 | 1 | 0 | 0 |
| 0 | 1 | 1 | 0 |
| 1 | 0 | 0 | 0 |
| 1 | 0 | 1 | 0 |
| 1 | 1 | 0 | 0 |
| 1 | 1 | 1 | 1 |

EXAMPLE 3-4

For the two input waveforms, *A* and *B*, in Figure 3-12, show the output waveform with its proper relation to the inputs.

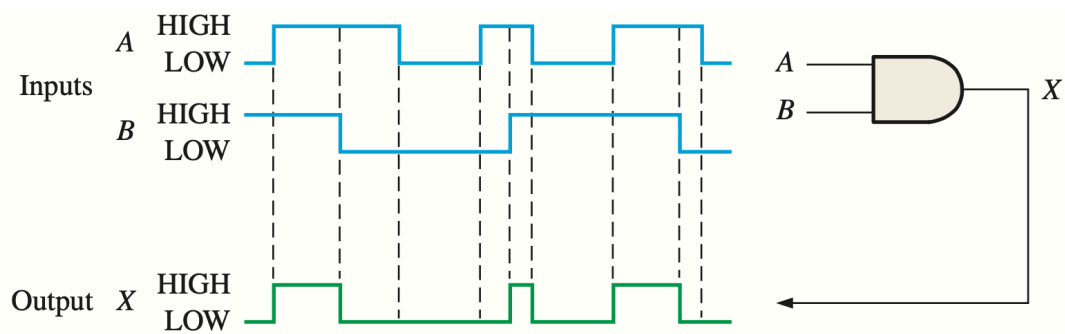


FIGURE 3-12

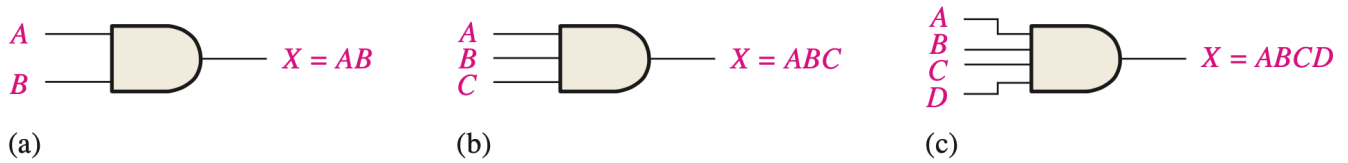


FIGURE 3-15 Boolean expressions for AND gates with two, three, and four inputs.

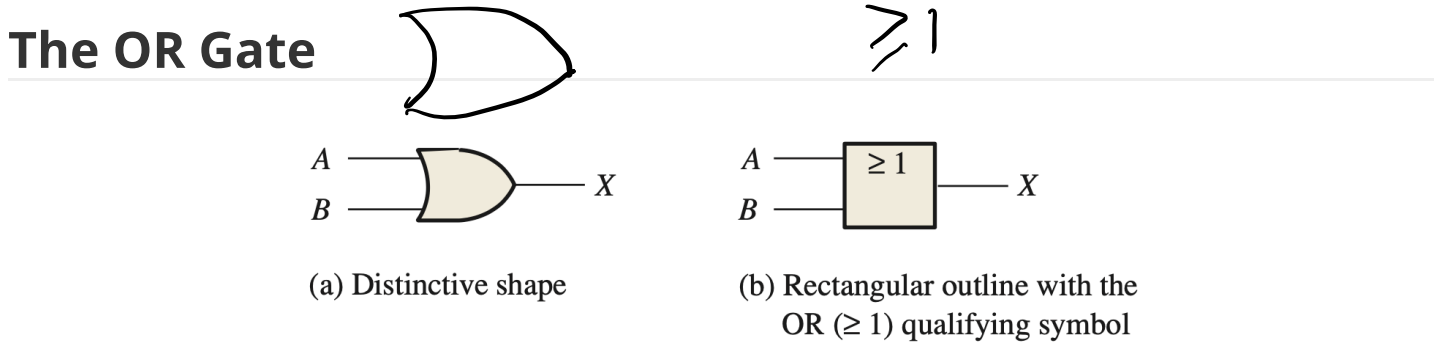


FIGURE 3-18 Standard logic symbols for the OR gate showing two inputs (ANSI/IEEE Std. 91-1984/Std. 91a-1991).

$$X = A + B$$

TABLE 3-5

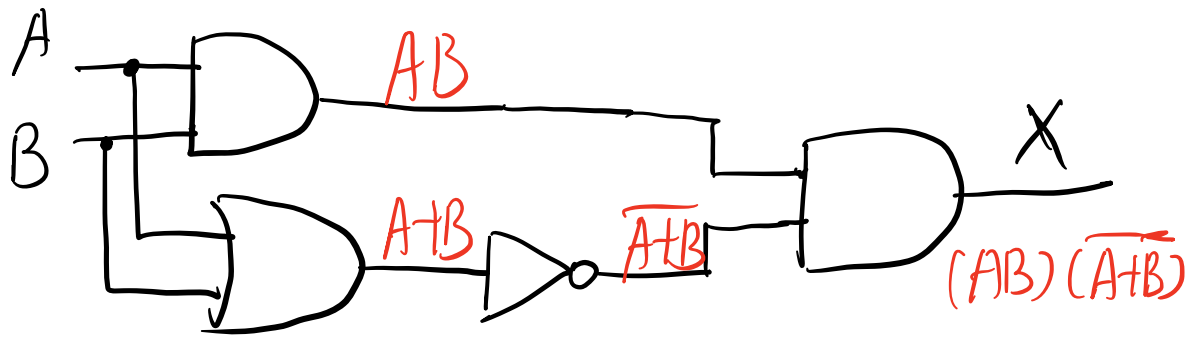
Truth table for a 2-input OR gate.

| Inputs | | Output |
|--------|---|--------|
| A | B | X |
| 0 | 0 | 0 |
| 0 | 1 | 1 |
| 1 | 0 | 1 |
| 1 | 1 | 1 |

1 = HIGH, 0 = LOW

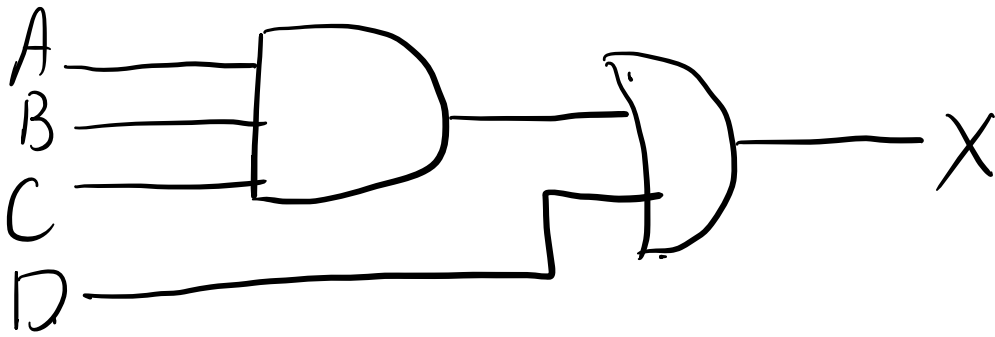
OR. AND NOT. Logic complete set.

NAND



$$X = (AB) \overline{(A+B)}$$

| A | B | X |
|---|---|---|
| 0 | 0 | 0 |
| 0 | 1 | 0 |
| 1 | 0 | 0 |
| 1 | 1 | 0 |



$$X = \overline{ABC} + \overline{D}$$

| A | B | C | D | X |
|---|---|---|---|----------------|
| 0 | 0 | 0 | 0 | 0 |
| 0 | 0 | 0 | 1 | 0 1 |
| 0 | 0 | 1 | 0 | 0 |
| 0 | 0 | 1 | 1 | 1 |
| 0 | 1 | 0 | 0 | 0 |

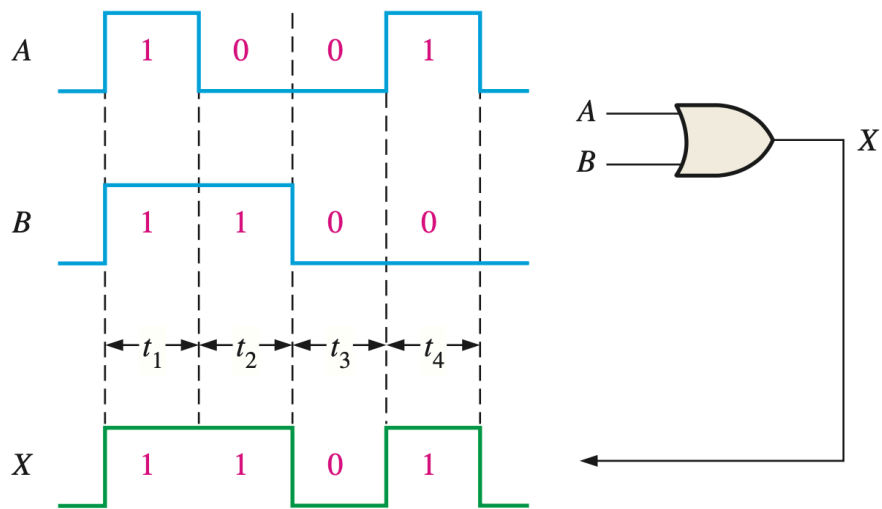


FIGURE 3-20 Example of OR gate operation with a timing diagram showing input and output time relationships.

EXAMPLE 3-9

For the 3-input OR gate in Figure 3-23, determine the output waveform in proper time relation to the inputs.

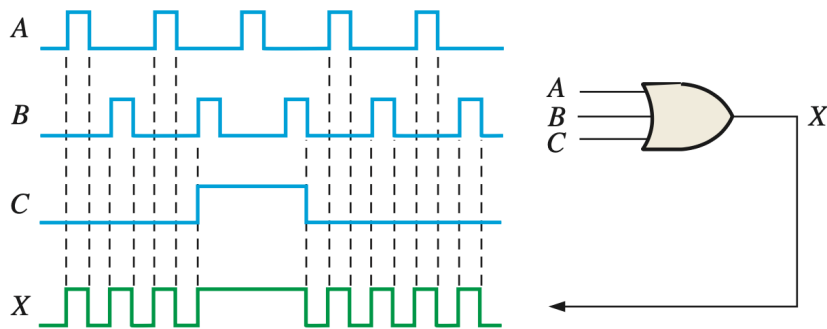


FIGURE 3-23

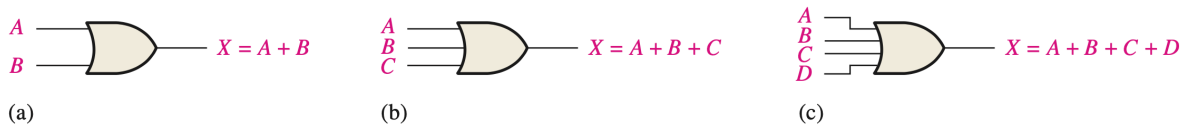


FIGURE 3-24 Boolean expressions for OR gates with two, three, and four inputs.

The NAND Gate

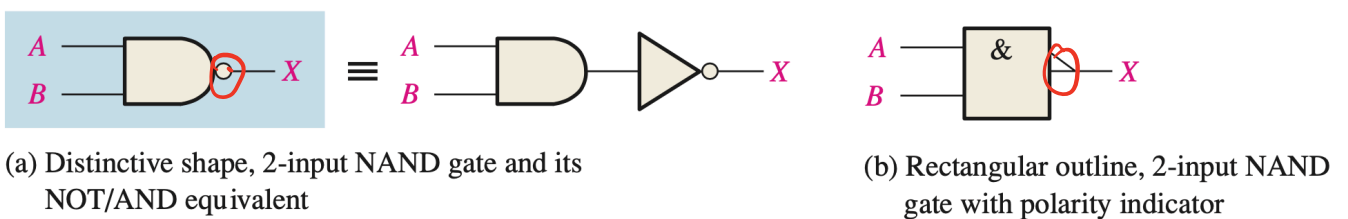


FIGURE 3-26 Standard NAND gate logic symbols (ANSI/IEEE Std. 91-1984/Std. 91a-1991).

$$X = \overline{AB}$$

TABLE 3-7

Truth table for a 2-input NAND gate.

| Inputs | | Output | |
|--------|---|--------|---|
| A | B | X | |
| 0 | 0 | 0 | 1 |
| 0 | 1 | 0 | 1 |
| 1 | 0 | 0 | 1 |
| 1 | 1 | 1 | 0 |

1 = HIGH, 0 = LOW.

EXAMPLE 3-11

Show the output waveform for the 3-input NAND gate in Figure 3-29 with its proper time relationship to the inputs.

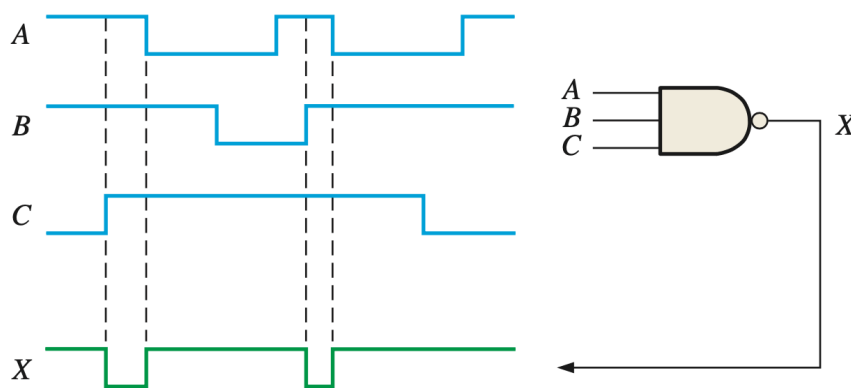
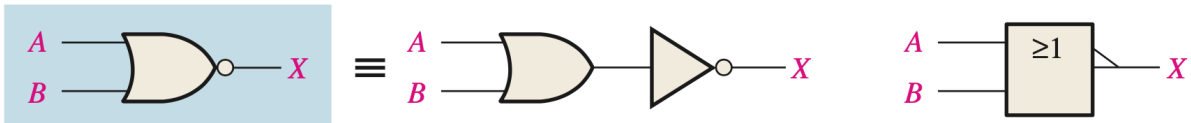


FIGURE 3-29

The NOR Gate

| A | B | X |
|---|---|---|
| 0 | 0 | 1 |
| 0 | 1 | 0 |
| 1 | 0 | 0 |
| 1 | 1 | 0 |

$$X = \overline{A+B}$$



(a) Distinctive shape, 2-input NOR gate and its NOT/OR equivalent

(b) Rectangular outline, 2-input NOR gate with polarity indicator

FIGURE 3-34 Standard NOR gate logic symbols (ANSI/IEEE Std. 91-1984/Std. 91a-1991).

EXAMPLE 3-16

Show the output waveform for the 3-input NOR gate in Figure 3-37 with the proper time relation to the inputs.

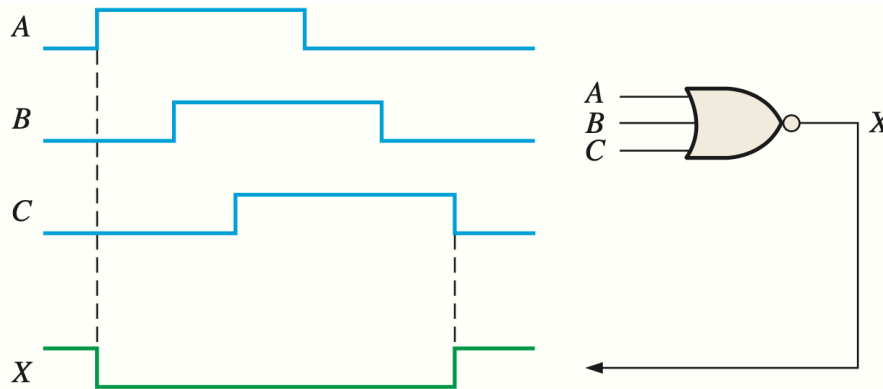


FIGURE 3-37

异或门

The Exclusive-OR and Exclusive-NOR Gates



(a) Distinctive shape

(b) Rectangular outline

FIGURE 3-42 Standard logic symbols for the exclusive-OR gate.

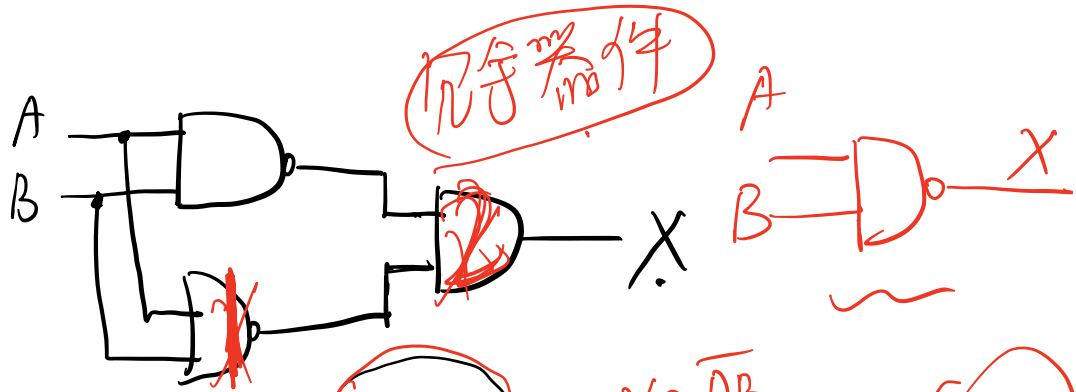


(a) Distinctive shape

(b) Rectangular outline

FIGURE 3-45 Standard logic symbols for the exclusive-NOR gate.

同或



$$X = \overline{(AB)} \cdot \overline{(A+B)}$$

$$X = \overline{AB}$$

$$\rightarrow X = \overline{AB}$$

| A | B | X |
|---|---|---|
| 0 | 0 | 1 |
| 0 | 1 | 0 |
| 1 | 0 | 0 |
| 1 | 1 | 0 |

IC

DATA

EDA

Synopsys
Cadence.

TABLE 3-13

An XOR gate used to add two bits.

异或门

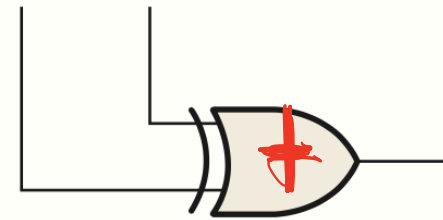
| Input Bits | | Output (Sum) |
|------------|---|--------------|
| A | B | Σ |

| | | |
|---|---|-----------------------------|
| 0 | 0 | 0 |
| 0 | 1 | 1 |
| 1 | 0 | 1 |
| 1 | 1 | 0 (without the 1 carry bit) |

异或 $X = A \oplus B$

$X = \overline{A \oplus B}$

同或 $= A \odot B$

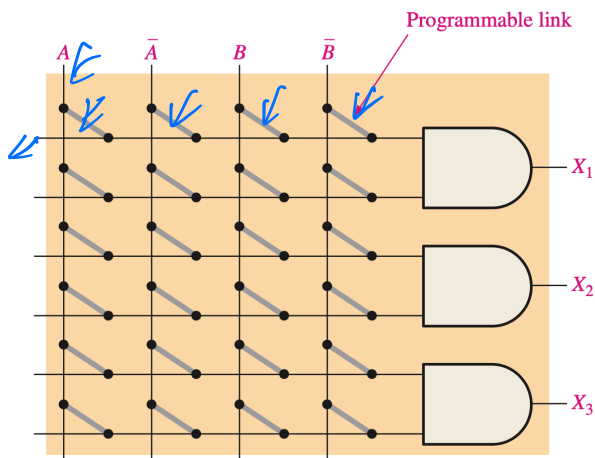


Programmable Logic

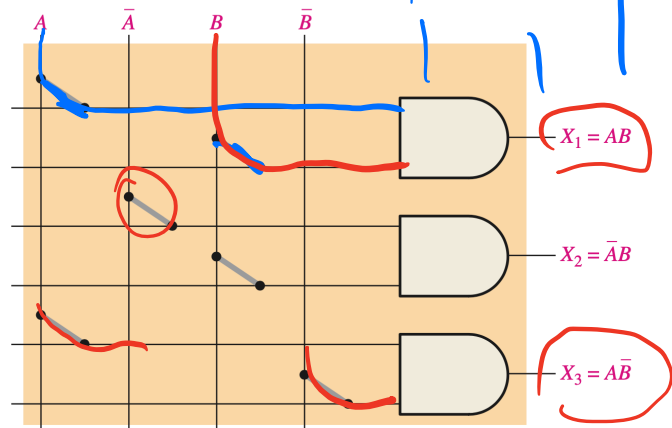
The AND Array

+ OR Array

| A | B | X |
|---|---|---|
| 0 | 0 | 1 |
| 0 | 1 | 0 |
| 1 | 0 | 0 |
| 1 | 1 | 1 |



(a) Unprogrammed



(b) Programmed

FIGURE 3-49 Concept of a programmable AND array.

Programmable Link Process Technologies

ve-

Fuse Technology

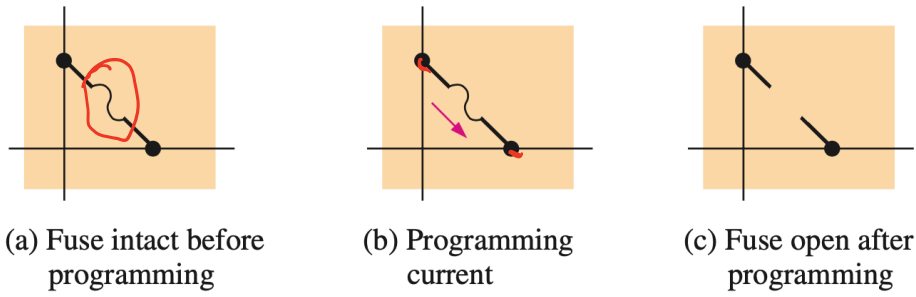


FIGURE 3-51 The programmable fuse link.

Antifuse Technology

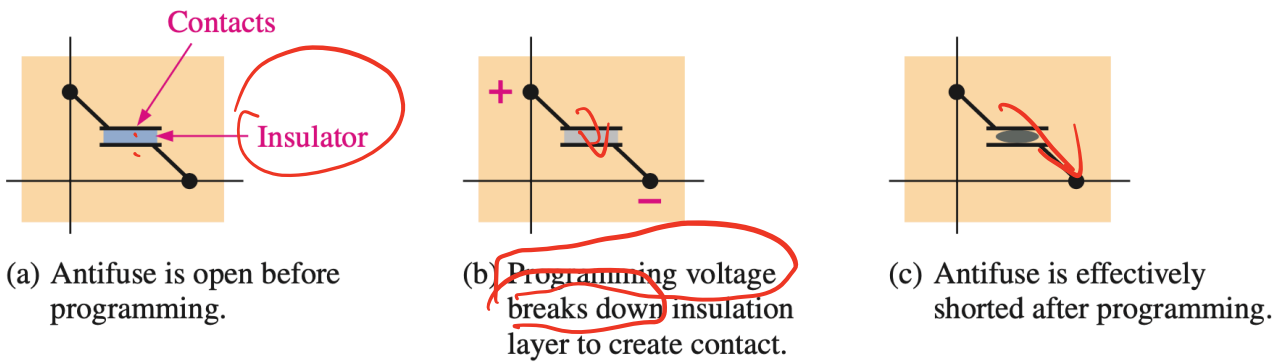


FIGURE 3-52 The programmable antifuse link.

EPROM Technology

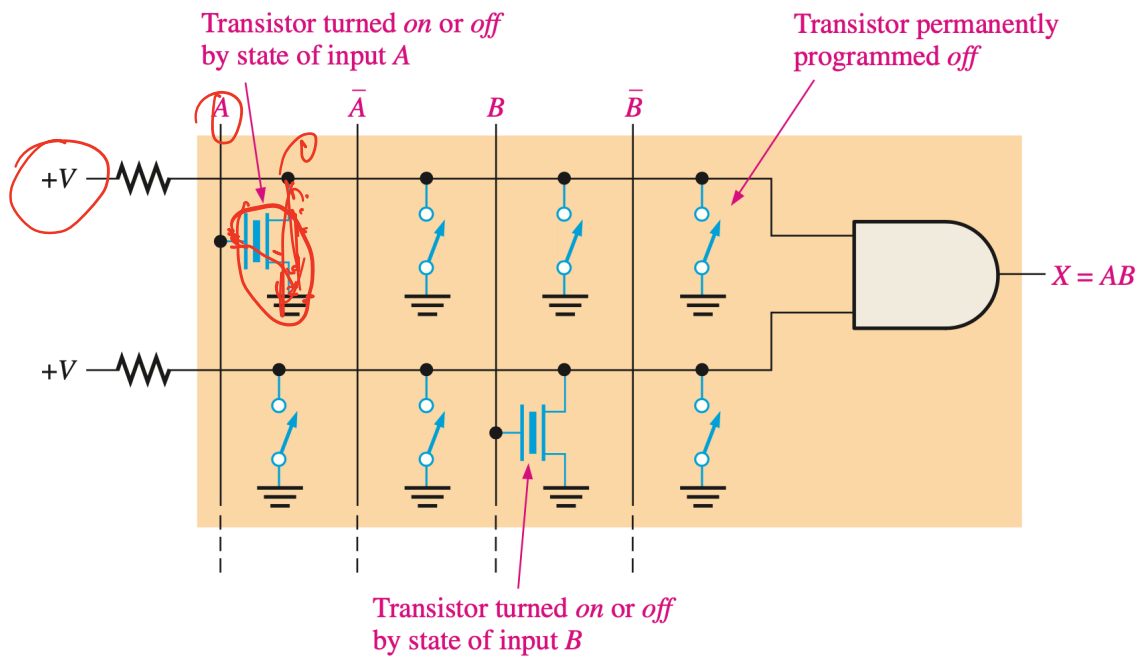


FIGURE 3-53 A simple AND array with EPROM technology. Only one gate in the array is shown for simplicity.

Flash Technology

Flash technology is based on a single transistor link and is both nonvolatile and reprogrammable. Flash elements are a type of EEPROM but are faster and result in higher density devices than the standard EEPROM link. A detailed discussion of the flash memory element can be found in Chapter 11.

SRAM Technology

Random
Static

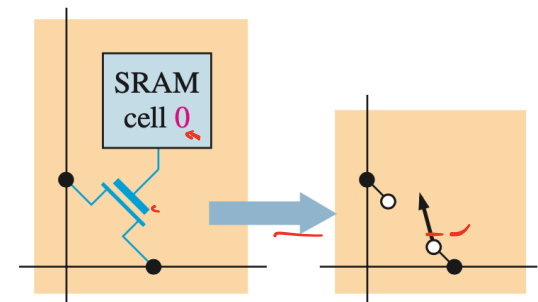
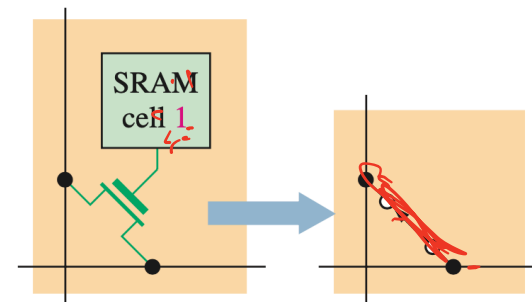
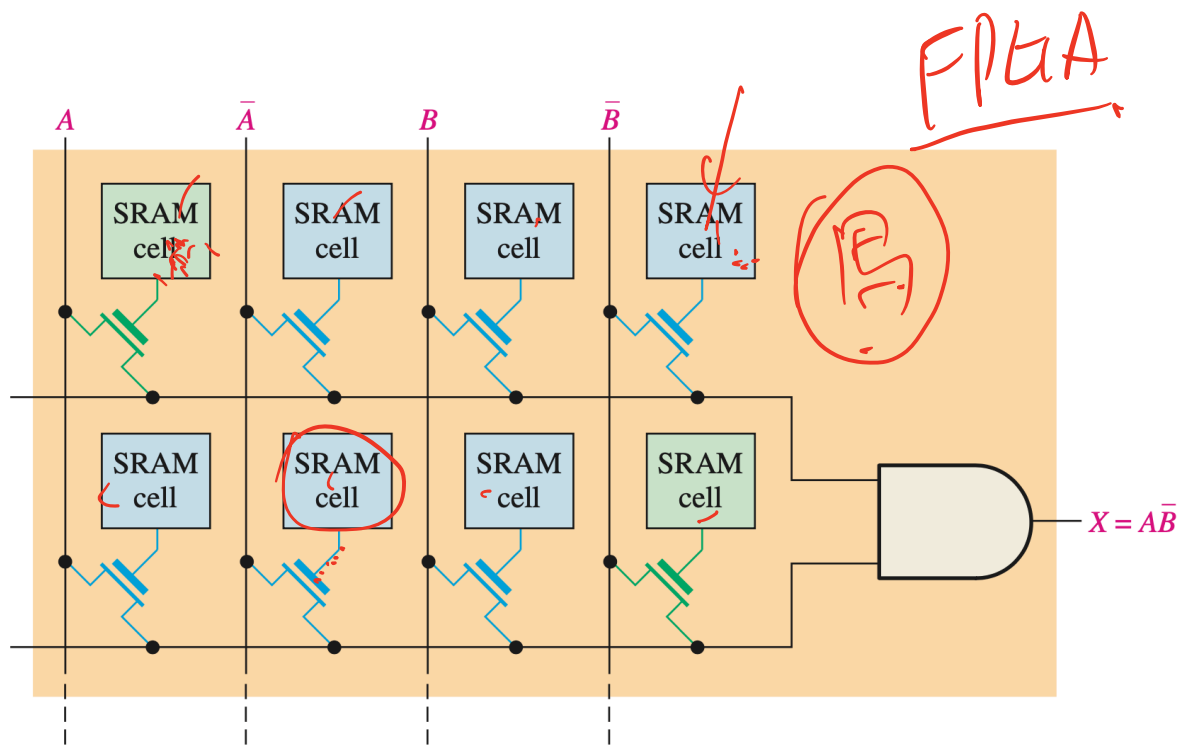


FIGURE 3-54 Concept of an AND array with SRAM technology.

IC.

TABLE 3-14

74 series logic families based on circuit technology.

| Circuit Type | Description | Circuit Technology |
|--------------|---------------------------------|--------------------|
| ABT | Advanced BiCMOS | BiCMOS |
| AC | Advanced CMOS | CMOS |
| ACT | Bipolar compatible AC | CMOS |
| AHC | Advanced high-speed CMOS | CMOS |
| AHCT | Bipolar compatible AHC | CMOS |
| ALB | Advanced low-voltage BiCMOS | BiCMOS |
| ALS | Advanced low-power Schottky | Bipolar |
| ALVC | Advanced low-voltage CMOS | CMOS |
| AUC | Advanced ultra-low-voltage CMOS | CMOS |
| AUP | Advanced ultra-low-power CMOS | CMOS |
| AS | Advanced Schottky | Bipolar |
| AVC | Advanced very-low-power CMOS | CMOS |
| BCT | Standard BiCMOS | BiCMOS |
| F | Fast | Bipolar |
| FCT | Fast CMOS technology | CMOS |
| HC | High-speed CMOS | CMOS |
| HCT | Bipolar compatible HC | CMOS |
| LS | Low-power Schottky | Bipolar |
| LV-A | Low-voltage CMOS | CMOS |
| LV-AT | Bipolar compatible LV-A | CMOS |
| LVC | Low-voltage CMOS | CMOS |
| LVT | Low-voltage biCMOS | BiCMOS |
| S | Schottky | Bipolar |

Propagation Delay Time

EXAMPLE 3-23

Show the propagation delay times of an inverter.

Solution

An input/output pulse of an inverter is shown in Figure 3-67, and the propagation delay times, t_{PHL} and t_{PLH} , are indicated. In this case, the delays are measured between the 50% points of the corresponding edges of the input and output pulses. The values of t_{PHL} and t_{PLH} are not necessarily equal but in many cases they are the same.

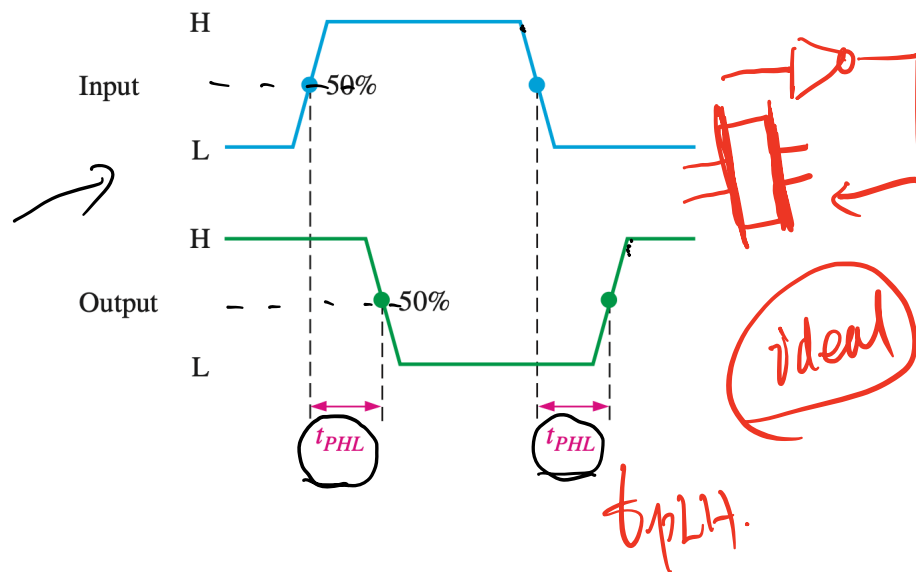


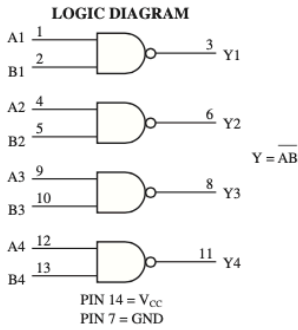
FIGURE 3-67

datasheets

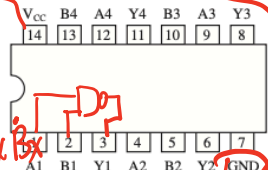
Quad 2-Input NAND Gate High-Performance Silicon-Gate CMOS

The MC54/74HC00A is identical in pinout to the LS00. The device inputs are compatible with Standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance With the JEDEC Standard No. 7A Requirements
- Chip Complexity: 32 FETs or 8 Equivalent Gates



Pinout 14-Lead Packages (Top View)



MC54/74HC00A

J SUFFIX
CERAMIC PACKAGE
CASE 632-08

N SUFFIX
PLASTIC PACKAGE
CASE 646-06

D SUFFIX
SOIC PACKAGE
CASE 751A-03

DT SUFFIX
TSSOP PACKAGE
CASE 948G-01

ORDERING INFORMATION

| | |
|-------------|---------|
| MC54HCXXAJ | Ceramic |
| MC74HCXXAN | Plastic |
| MC74HCXXAD | SOIC |
| MC74HCXXADT | TSSOP |

| Inputs | | Output |
|--------|---|--------|
| A | B | Y |
| L | L | H |
| L | H | H |
| H | L | H |
| H | H | L |

MAXIMUM RATINGS*

| Symbol | Parameter | Value | Unit |
|-----------|---|------------------------|--------------|
| V_{CC} | DC Supply Voltage (Referenced to GND) | -0.5 to +7.0 | V |
| V_{in} | DC Input Voltage (Referenced to GND) | -0.5 to $V_{CC} + 0.5$ | V |
| V_{out} | DC Output Voltage (Referenced to GND) | -0.5 to $V_{CC} + 0.5$ | V |
| I_{in} | DC Input Current, per Pin | ± 20 | mA |
| I_{out} | DC Output Current, per Pin | ± 25 | mA |
| I_{CC} | DC Supply Current, V_{CC} and GND Pins | ± 50 | mA |
| P_D | Power Dissipation in Still Air, Plastic or Ceramic DIP† | 750 | mW |
| | SOIC Package† | 500 | |
| | TSSOP Package† | 450 | |
| T_{stg} | Storage Temperature | -65 to +150 | $^{\circ}$ C |
| T_L | Lead Temperature, 1 mm from Case for 10 Seconds | 260 | $^{\circ}$ C |
| | Plastic DIP, SOIC or TSSOP Package | | |
| | Ceramic DIP | 300 | |

* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

† Derating — Plastic DIP: -10 mW/ $^{\circ}$ C from 65 $^{\circ}$ to 125 $^{\circ}$ C
Ceramic DIP: -10 mW/ $^{\circ}$ C from 100 $^{\circ}$ to 125 $^{\circ}$ C
SOIC Package: -7 mW/ $^{\circ}$ C from 65 $^{\circ}$ to 125 $^{\circ}$ C
TSSOP Package: -6.1 mW/ $^{\circ}$ C from 65 $^{\circ}$ to 125 $^{\circ}$ C

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | in | Max | Unit |
|-------------------|--|------------------|----------|--------------|
| V_{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| V_{in}, V_{out} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | V_{CC} | V |
| T_A | Operating Temperature, All Package Types | -55 | +125 | $^{\circ}$ C |
| t_r, t_f | Input Rise and Fall Time | $V_{CC} = 2.0$ V | 0 | 1000 |
| | | $V_{CC} = 4.5$ V | 0 | 500 |
| | | $V_{CC} = 6.0$ V | 0 | 400 |

DC CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Condition | V_{CC} V | Guaranteed Limit | | | Unit |
|----------|--|---|--------------------------|------------------------------|------------------------------|------------------------------|---------|
| | | | | -55 to 25 $^{\circ}$ C | $\leq 85^{\circ}$ C | $\leq 125^{\circ}$ C | |
| V_{IH} | Minimum High-Level Input Voltage | $V_{out} = 0.1V$ or $V_{CC} - 0.1V$ $ I_{out} \leq 20\mu A$ | 2.0 3.0 4.5 6.0 | 1.50 2.10 3.15 4.20 | 1.50 2.10 3.15 4.20 | 1.50 2.10 3.15 4.20 | V |
| V_{IL} | Maximum Low-Level Input Voltage | $V_{out} = 0.1V$ or $V_{CC} - 0.1V$ $ I_{out} \leq 20\mu A$ | 2.0 3.0 4.5 6.0 | 0.50 0.90 1.35 1.80 | 0.50 0.90 1.35 1.80 | 0.50 0.90 1.35 1.80 | V |
| V_{OH} | Minimum High-Level Output Voltage | $V_{in} = V_{IH}$ or V_{IL} $ I_{out} \leq 20\mu A$ | 2.0 4.5 6.0 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | V |
| | | $V_{in} = V_{IH}$ or V_{IL} $ I_{out} \leq 2.4mA$ $ I_{out} \leq 4.0mA$ $ I_{out} \leq 5.2mA$ | 3.0 4.5 6.0 | 2.48 3.98 5.48 | 2.34 3.84 5.34 | 2.20 3.70 5.20 | |
| V_{OL} | Maximum Low-Level Output Voltage | $V_{in} = V_{IH}$ or V_{IL} $ I_{out} \leq 20\mu A$ | 2.0 4.5 6.0 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | V |
| | | $V_{in} = V_{IH}$ or V_{IL} $ I_{out} \leq 2.4mA$ $ I_{out} \leq 4.0mA$ $ I_{out} \leq 5.2mA$ | 3.0 4.5 6.0 | 0.26 0.26 0.26 | 0.33 0.33 0.33 | 0.40 0.40 0.40 | |
| I_{in} | Maximum Input Leakage Current | $V_{in} = V_{CC}$ or GND | 6.0 | ± 0.1 | ± 1.0 | ± 1.0 | μ A |
| I_{CC} | Maximum Quiescent Supply Current (per Package) | $V_{in} = V_{CC}$ or GND $I_{out} = 0\mu A$ | 6.0 | 1.0 | 10 | 40 | μ A |

AC CHARACTERISTICS ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

| Symbol | Parameter | V_{CC} V | Guaranteed Limit | | | Unit |
|-----------|---|---------------|---|---------------------|----------------------|------|
| | | | -55 to 25 $^{\circ}$ C | $\leq 85^{\circ}$ C | $\leq 125^{\circ}$ C | |
| t_{PLH} | Maximum Propagation Delay, Input A or B to Output Y | 2.0 | 75 | 95 | 110 | ns |
| t_{PHL} | | 3.0 | ≤ 50 | 40 | 55 | |
| | | 4.5 | 15 | 19 | 22 | |
| | | 6.0 | 13 | 16 | 19 | |
| t_{TLH} | Maximum Output Transition Time, Any Output | 2.0 | 75 | 95 | 110 | ns |
| t_{THL} | | 3.0 | 27 | 32 | 36 | |
| | | 4.5 | 15 | 19 | 22 | |
| | | 6.0 | 13 | 16 | 19 | |
| C_{in} | Maximum Input Capacitance | | 10 | 10 | 10 | pF |
| C_{PD} | Power Dissipation Capacitance (Per Buffer) | | Typical @ 25 $^{\circ}$ C, $V_{CC} = 5.0$ V, $V_{EE} = 0$ V | | | pF |
| | | | 22 | | | |

FIGURE 3-65 CMOS logic. Partial data sheet for a 54/74HC00A quad 2-input NAND gate. The 54 prefix indicates military grade and the 74 prefix indicates commercial grade.

DC Supply Voltage

The typical dc supply voltage for CMOS logic is either 5 V, 3.3 V, 2.5 V, or 1.8 V, depending on the category. An advantage of CMOS is that the supply voltages can vary over a wider range than for bipolar logic. The 5 V CMOS can tolerate supply variations from 2 V to 6 V and still operate properly although propagation delay time and power dissipation are significantly affected. The 3.3 V CMOS can operate with supply voltages from 2 V to 3.6 V. The typical dc supply voltage for bipolar logic is 5.0 V with a minimum of 4.5 V and a maximum of 5.5 V.

Power Dissipation

$$P_D = V_{CC} \left(\frac{I_{CCH} + I_{CCL}}{2} \right)$$

The HC family, for example, has a power of 2.75 mW/gate at 0 Hz (quiescent) and 600 mW/gate at 1 MHz.

Input and Output Logic Levels

V_{IL} is the LOW level input voltage for a logic gate, and V_{IH} is the HIGH level input voltage. The 5 V CMOS accepts a maximum voltage of 1.5 V as V_{IL} and a minimum voltage of 3.5 V as V_{IH} . Bipolar logic accepts a maximum voltage of 0.8 V as V_{IL} and a minimum voltage of 2 V as V_{IH} .

V_{OL} is the LOW level output voltage and V_{OH} is the HIGH level output voltage. For 5 V CMOS, the maximum V_{OL} is 0.33 V and the minimum V_{OH} is 4.4 V. For bipolar logic, the maximum V_{OL} is 0.4 V and the minimum V_{OH} is 2.4 V. All values depend on operating conditions as specified on the data sheet.

Speed-Power Product (SPP)

$$SPP = t_p P_D$$

This parameter (**speed-power product**) can be used as a measure of the performance of a logic circuit taking into account the propagation delay time and the power dissipation.

EXAMPLE 3-24

A certain gate has a propagation delay of 5 ns and $I_{CCH} = 1$ mA and $I_{CCL} = 2.5$ mA with a dc supply voltage of 5 V. Determine the speed-power product.

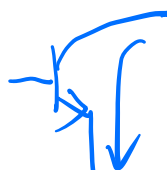
Solution

$$P_D = V_{CC} \left(\frac{I_{CCH} + I_{CCL}}{2} \right) = 5 \text{ V} \left(\frac{1 \text{ mA} + 2.5 \text{ mA}}{2} \right) = 5 \text{ V}(1.75 \text{ mA}) = 8.75 \text{ mW}$$

$$SPP = (5 \text{ ns})(8.75 \text{ mW}) = 43.75 \text{ pJ}$$

Fan-Out and Loading

$$\text{Unit loads} = \frac{I_{OL}}{I_{IL}} = \frac{8.0 \text{ mA}}{0.4 \text{ mA}} = 20$$



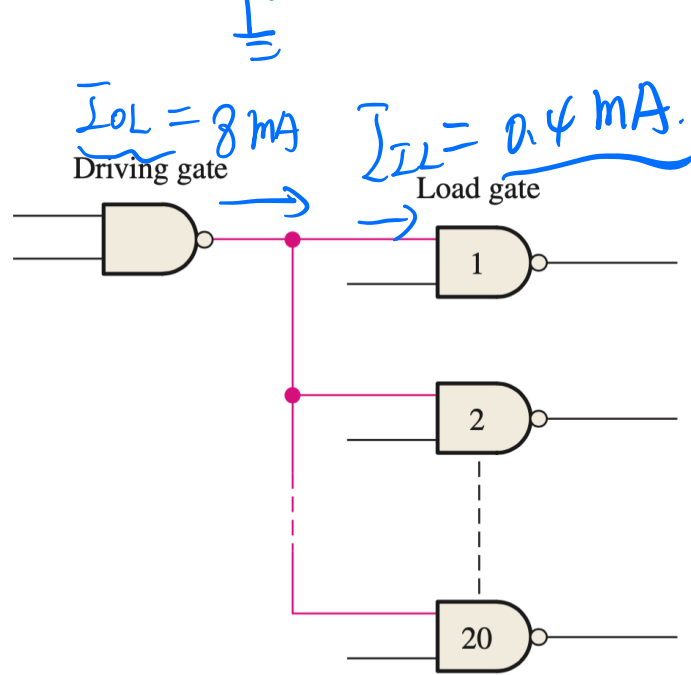
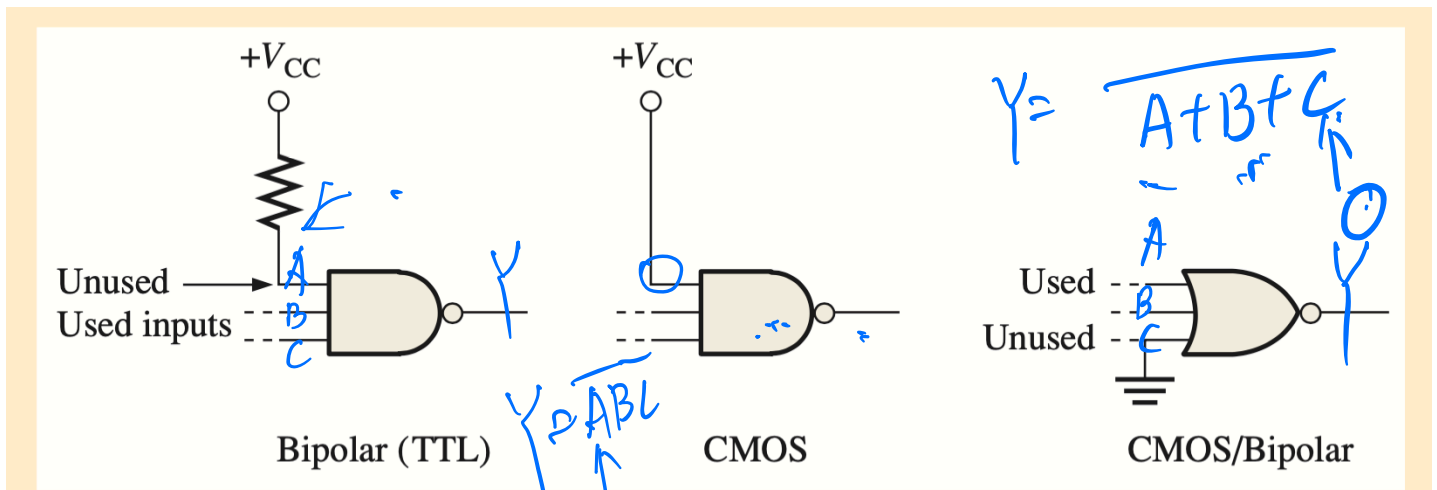


FIGURE 3-68 The LS family NAND gate output fans out to a maximum of 20 LS family gate inputs.

Unused inputs



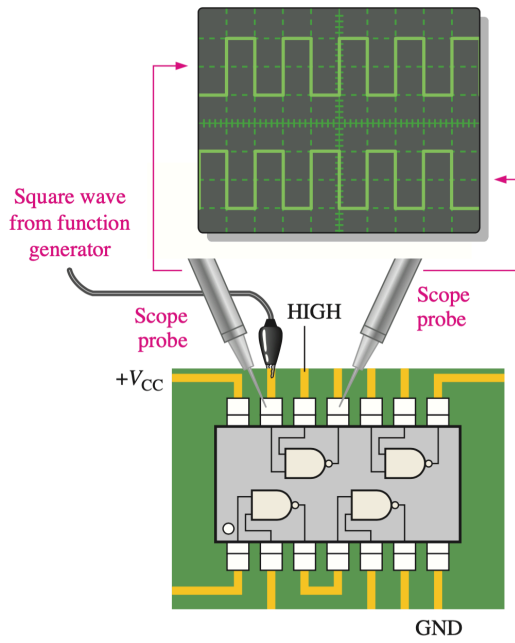
Troubleshooting



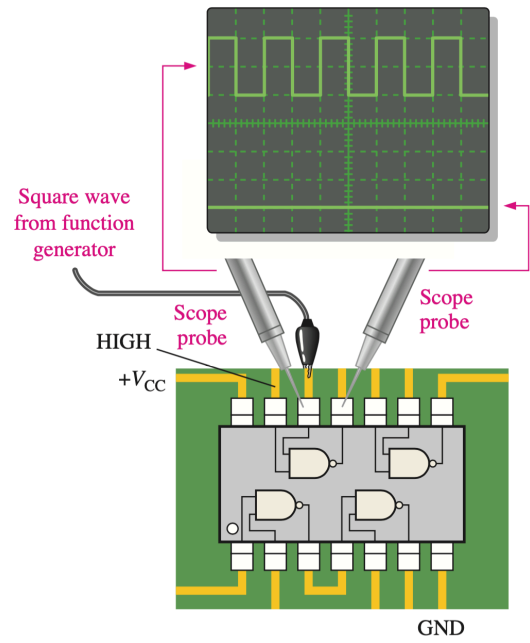
(a) Application of pulses to the open input will produce no pulses on the output.

(b) Application of pulses to the good input will produce output pulses for bipolar NAND and AND gates because an open input typically acts as a HIGH. It is uncertain for CMOS.

FIGURE 3-69 The effect of an open input on a NAND gate.

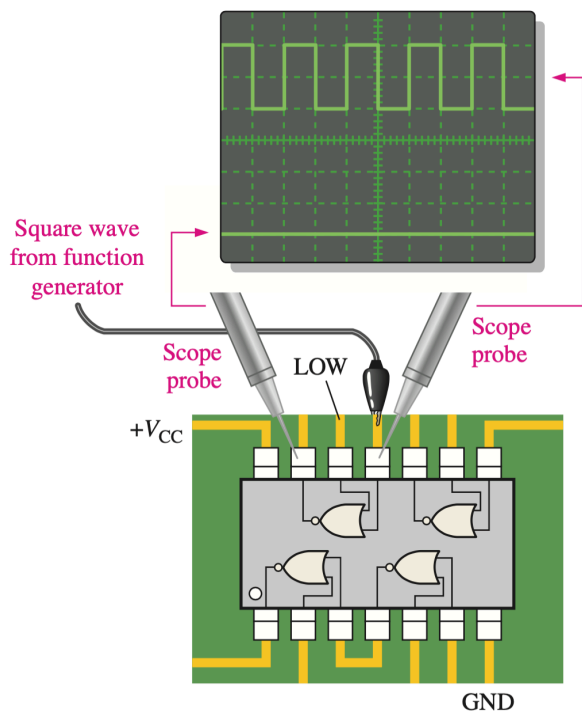


(a) Pin 13 input and pin 11 output OK

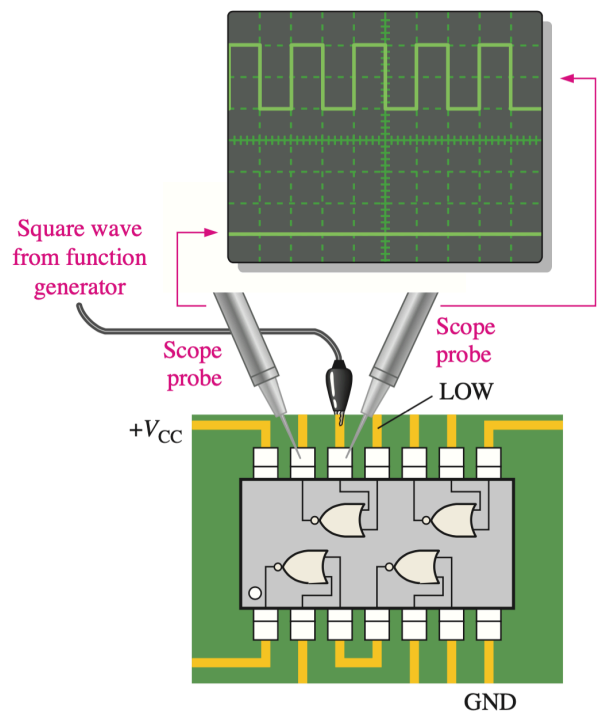


(b) Pin 12 input is open.

FIGURE 3-70 Troubleshooting a NAND gate for an open input.

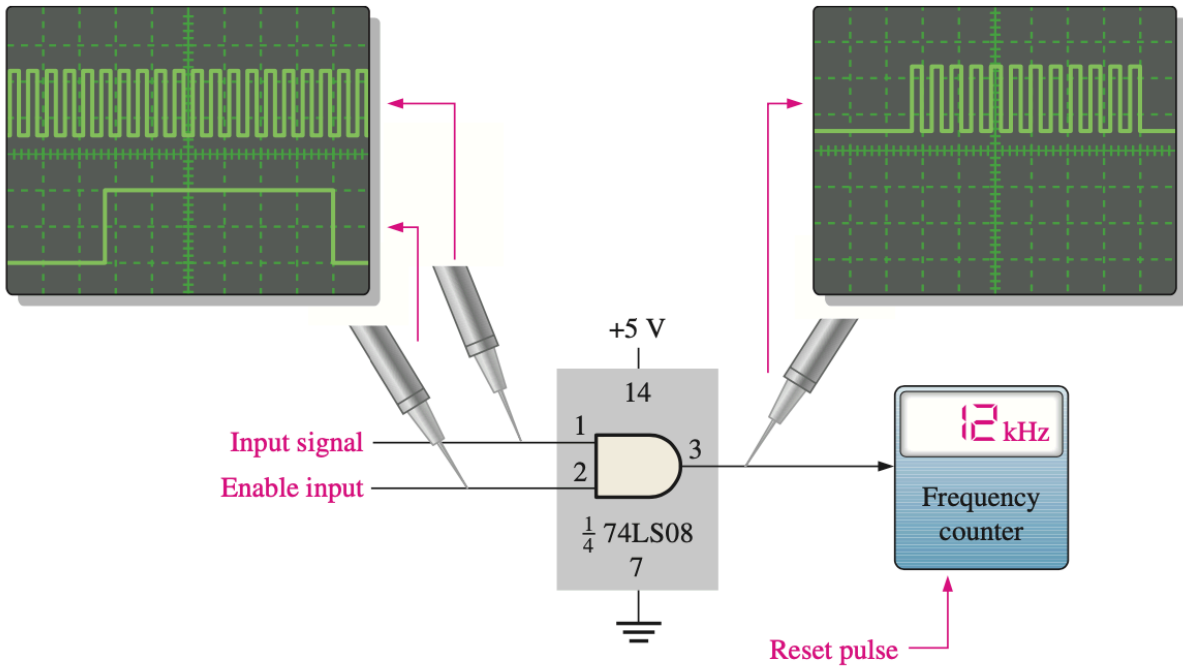


(a) Pulse input on pin 11. No pulse output.

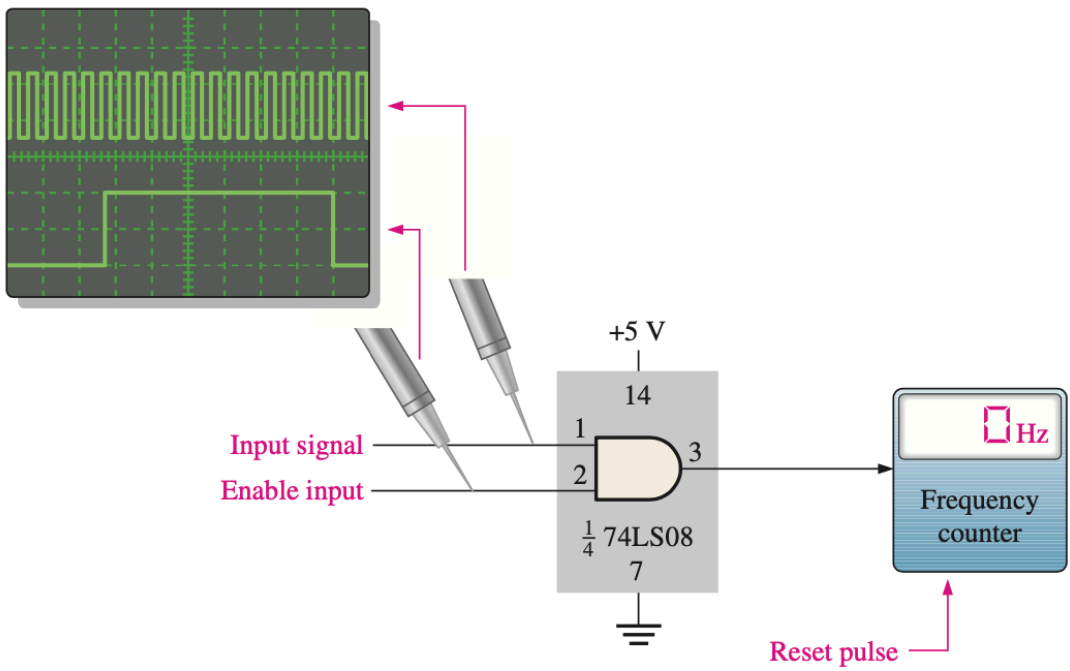


(b) Pulse input on pin 12. No pulse output.

FIGURE 3-71 Troubleshooting a NOR gate for an open output.

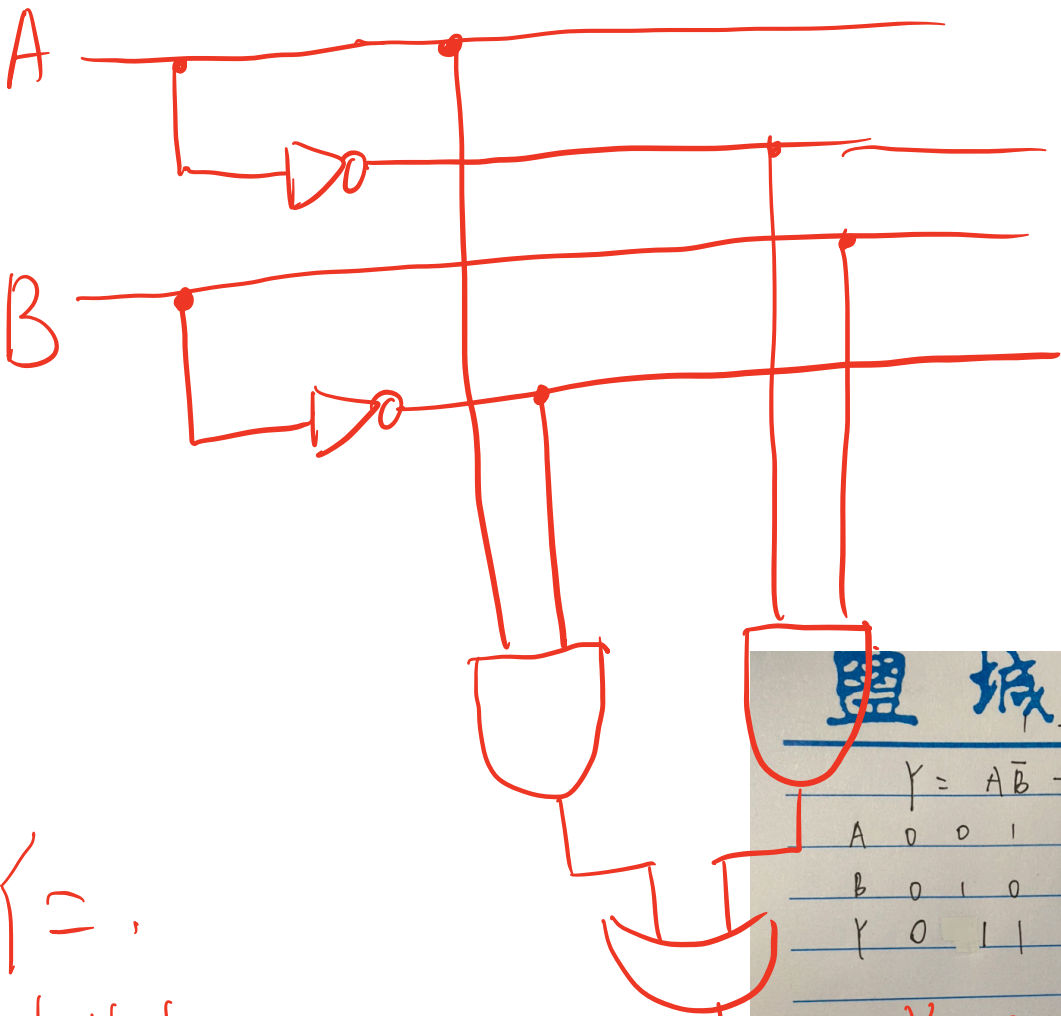


(a) The counter is working properly.



(b) The counter is not measuring a frequency.

FIGURE 3-73



Y =
真值表

描述一下逻辑功能

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$$Y = A\bar{B} + \bar{A}B$$

| | | | | |
|---|---|---|---|---|
| A | 0 | 0 | 1 | 1 |
| B | 0 | 1 | 0 | 1 |
| Y | 0 | 1 | 1 | 0 |

$$Y = A\bar{B} + \bar{A}B = A \oplus B$$